

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPG20N06S4L-14A	**Issued**	02. June 2021
MA#	MA002193032		
Package	PG-TDSON-8-10	**Weight***	100.13 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.345	1.34	1.34	13434	13434
chip_2	inorganic material	silicon	7440-21-3	1.345	1.34	1.34	13434	13434
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		131	
	non noble metal	iron	7439-89-6	0.044	0.04		437	
	non noble metal	copper	7440-50-8	43.681	43.64	43.69	436267	436835
wire	non noble metal	aluminium	7429-90-5	0.828	0.83	0.83	8270	8270
encapsulation	organic material	carbon black	1333-86-4	0.090	0.09		896	
	plastics	epoxy resin	-	6.368	6.36		63601	
	inorganic material	silicondioxide	60676-86-0	38.388	38.34	44.79	383400	447897
leadfinish	non noble metal	tin	7440-31-5	1.396	1.39	1.39	13947	13947
plating	inorganic material	phosphorus	7723-14-0	0.001			14	
	non noble metal	nickel	7440-02-0	0.603	0.60	0.60	6023	6037
solder	non noble metal	tin	7440-31-5	0.066	0.07		663	
	noble metal	silver	7440-22-4	0.083	0.08		829	
	non noble metal	lead	7439-92-1	3.170	3.17	3.32	31664	33156
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			27	
	non noble metal	copper	7440-50-8	2.699	2.70	2.70	26955	26990
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com